



## DO-221AC(SMAF)

F	Primary Characteristics					
	l <sub>F</sub>	5	Α			
	$V_{RRM}$	20~200	V			
	I <sub>FSM</sub>	100	Α			
	$V_{F}$	0.55 , 0.70 , 0.85 , 0.87 , 0.90	V			
	T <sub>J</sub> max	125,150	°C			

#### **Features**

- · Low Profile Package
- · Ideal for Automated Placement
- · Guard Ring for Over Voltage Protection
- · Low Forward Voltage Drop

#### **Mechanical Data**

· Case: DO-221AC (SMAF)

 $\bullet \ \mathsf{Case} \ \mathsf{Material} : \mathsf{Molded} \ \mathsf{Plastic}. \ \mathsf{UL} \ \mathsf{Flammability}$ 

Classification Rating 94V-0

Terminals: Lead free Plating (Tin Finish)
Solderable per MIL-STD-202, Method 208

Polarity : Cathode Band

Ordering Information							
Part No. Remark		Package	Packing				
SM5xxxAF	RoHS Compliant						
SM5xxxAF-H	SM5xxxAF-H Halogen Free		10000 / Tape & Reel				
SM5xxxAF-Q	AEC-Q101 qualified						

Maximum Ratings (TA=25°C unless otherwise noted)											
Parameter	Symbol	SM5 20AF	SM5 30AF	SM5 40AF	SM5 50AF	SM5 60AF	SM5 80AF	SM5 100AF	SM5 150AF	SM5 200AF	Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	30	40	50	60	80	100	150	200	V
Maximum RMS Voltage	$V_{RMS}$	14	21	28	35	42	56	70	105	140	V
Maximum DC Blocking Voltage	$V_{DC}$	20	30	40	50	60	80	100	150	200	V
Maximum Average Forward Rectified Current	I <sub>F</sub>		5.0					Α			
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>		100.0					Α			
Maximum Instantaneous Forward Voltage IF=5A @ 25°C	V <sub>F</sub>		0.55		0.7	70	0.	85	0.87	0.90	V
Maximum DC Reverse Current @ Tc=25°C at Rated DC Blocking Voltage @ Tc=100°C	I <sub>R</sub>	0.5 10 0.2 5.0				mA					
Typical Junction Capacitance (NOTE1)	C <sub>j</sub>		300		2	10	1	70	150	110	pF
Typical Thermal Resistance	$R_{\theta JA}$	120			°C/W						
Operating Temperature Range	TJ	-55 to +125 -55 to +150			°C						
Storage Temperature Range	T <sub>STG</sub>	-55 to +150			°C						
NOTEC:											

#### NOTES:

<sup>1.</sup>Measured at 1.0MHz and applied reverse voltage of 4.0V DC.





#### **Rating and Characteristics Curves**

FIG. 1-Typical Forward Current Derating Curve

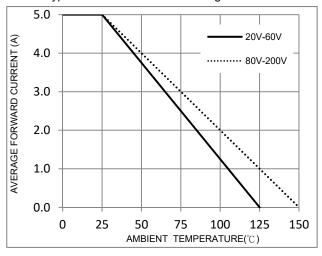


FIG. 3-Maximum Non-Repetitive Forward Surge Current

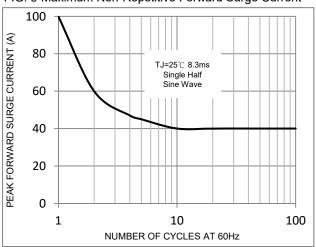


FIG. 5-Typical Junction Capacitance

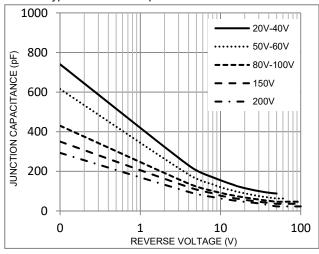


FIG. 2-Typical Forward Characteristics

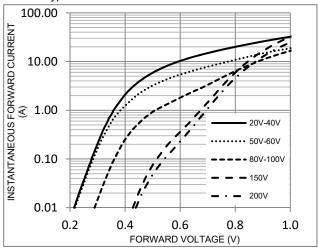
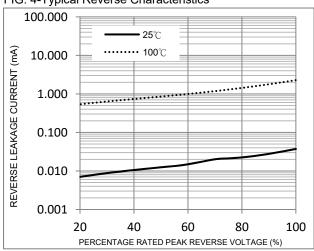
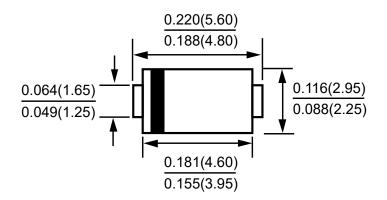


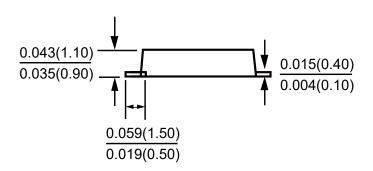
FIG. 4-Typical Reverse Characteristics





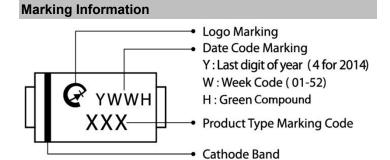
#### **Package Outline Dimensions**





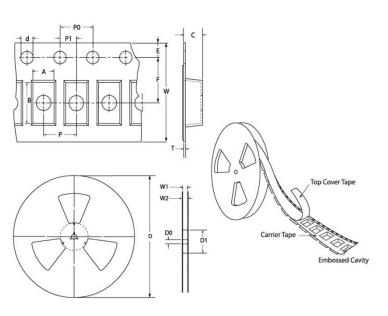
## DO-221AC(SMAF)

Dimensions in inches and (millimeters)



Suggested Pad Layout							
Outline Dimension	SMAF (mm)						
Α	6.50						
В	1.50	c  +     +					
С	1.70	- D B -					
D	2.50	A —					
Е	4.00						

Tape & Reel Specification						
Item	Symbol	SMAF(mm)				
item	Symbol	DO-221AC				
Carrier width	Α	3 ± 0.1				
Carrier length	В	5.6 ± 0.1				
Carrier depth	С	1.2 ± 0.1				
Sprocket hole	d	1.50 ± 0.1				
Reel outside diameter	D	330 ± 2.0				
Feed hole diameter	D0	13.5 ± 1				
Reel inner diameter	D1	50 (min.)				
Sprocket hole position	Е	1.75 ± 0.1				
Punch hole position	F	5.5 ± 0.05				
Sprocket hole pitch	Р	4.0 ± 0.1				
Sprocket hole pitch	P0	4.0 ± 0.05				
Embossment center	P1	2.0 ± 0.05				
Overall tape thickness	Т	0.25 ± 0.05				
Tape width	W	12.0 ± 0.2				
Reel width	W2	18.4 (max)				
Reel width	W1	14.4 (max)				





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